

Formation of interfacial η' -Cu₆Sn₅ in Sn–0.7Cu/Cu solder joints during isothermal aging – ERRATUM

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In the first paragraph, this sentence was cited incorrectly. The cited work was done by Nogita et al.

Importantly, the density changes with the structural evolutions. It may be catastrophic to the intrinsically brittle IMC as reported by Nogita et al. that more cracks were observed at the interface of Sn–Cu/Cu if no Ni was added to inhibit the transformation.⁴

The correct citation is as follows:

Importantly, the density changes with the structural evolutions. It may be catastrophic to the intrinsically

brittle IMC as reported by Nogita et al. that more cracks were observed at the interface of Sn–Cu/Cu if no Ni was added to inhibit the transformation.⁸

The publisher regrets the error.

Reference

Zhongbing Luo, Lai Wang, Qinqin Fu, Chongqian Cheng, and Jie Zhao: Formation of interfacial η' -Cu₆Sn₅ in Sn–0.7Cu/Cu solder joints during isothermal aging. *J. Mater. Res.* **27**, 1468 (2011).